

3A Avg.

150 Volts

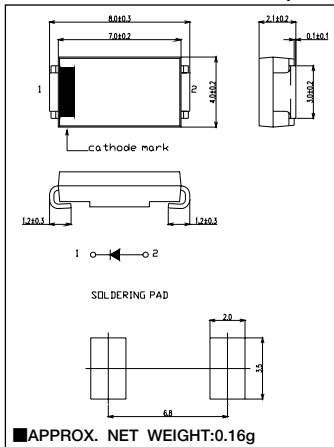
SBD

NSH03A15

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	150	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_I=109^\circ\text{C}, V_{RM}=150\text{V}$ T_I : Lead Temperature 3.0 A
		—	$T_a=28^\circ\text{C}, V_{RM}=150\text{V}^*$ 1.4 A
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	4.71	A
サージ順電流 Surge Forward Current	I_{FSM}	60 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^\circ\text{C}$

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	—	—	1	mA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^\circ\text{C}, I_{FM}=3\text{A}$	—	—	0.90	V
熱抵抗 Thermal Resistance	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	89	$^\circ\text{C}/\text{W}$
	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	アルミナ基板実装*		13	$^\circ\text{C}/\text{W}$

*アルミナ基板実装 / Alumina Substrate Mounted (Soldering Land=2×3.5mm, Both Side)

■定格・特性曲線

